

# TinyLogic UHS Dual 2-Input OR Gate

# NC7WZ32

#### Description

The NC7WZ32 is a dual 2–Input OR Gate from **onsemi**'s Ultra High Speed Series of TinyLogic. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a very broad  $V_{CC}$  operating range. The device is specified to operate over the 1.65 V to 5.5 V  $V_{CC}$  range. The inputs and output are high impedance when  $V_{CC}$  is 0 V. Inputs tolerate voltages up to 6.5 V independent of  $V_{CC}$  operating voltage.

#### **Features**

- Space Saving US8 Surface Mount Package
- MicroPak<sup>TM</sup> Pb-Free Leadless Package
- Ultra High Speed:  $t_{PD} = 2.4$  ns Typ. into 50 pF at 5 V  $V_{CC}$
- High Output Drive: ±24 mA at 3 V V<sub>CC</sub>
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.5 V
- Matches the Performance of LCX when Operated at 3.3 V V<sub>CC</sub>
- Power Down High Impedance Inputs / Output
- Overvoltage Tolerant Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry Implemented
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

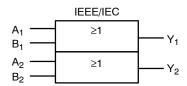


Figure 1. Logic Symbol

# MARKING DIAGRAMS



UQFN8 1.6X1.6, 0.5P CASE 523AY





US8 CASE 846AN



N5, WZ32 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code
XY = 2-Digit Date Code Format
Z = Assembly Plant Code
A = Assembly Location
L = Wafer Lot Number
YW = Assembly Start Week

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

# **Connection Diagrams**

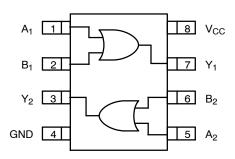


Figure 2. Connection Diagram (Top View)

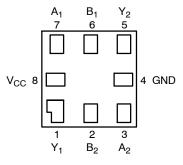
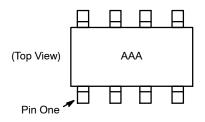


Figure 4. Pad Assignments for MicroPak (Top Thru View)



AAA represents Product Code Top Mark - see ordering code

NOTE: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Figure 3. Pin One Orientation Diagram

## **PIN DESCRIPTIONS**

Pin Names	Description
A <sub>n</sub> , B <sub>n</sub>	Inputs
Y <sub>n</sub>	Output

## **FUNCTION TABLE** (Y = A + B)

Inp	Output	
Α	В	Υ
L	L	L
L	Н	Н
Н	L	Н
Н	Н	Н

H = HIGH Logic Level L = LOW Logic Level

#### NC7WZ32

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parame	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage	Supply Voltage			V
V <sub>IN</sub>	DC Input Voltage		-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < 0 V	-	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < 0 V	-	-50	mA
I <sub>OUT</sub>	DC Output Current	-	±50	mA	
I <sub>CC</sub> / I <sub>GND</sub>	DC V <sub>CC</sub> / GND Current	-	±100	mA	
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
TJ	Junction Temperature under Bias		-	150	°C
$T_L$	Junction Lead Temperature (Soldering, 10 Seconds)		-	260	°C
P <sub>D</sub>	Power Dissipation in Still Air US8		-	500	mW
		MicroPak-8	-	539	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### RECOMMENDED OPERATING CONDITIONS

Symbol		Parameter	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Rete	ntion	1.5	5.5	
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature		-40	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time V <sub>CC</sub> = 1.80 V ±0.15 V, 2.5 V ±0.2 V		0	20	ns/V
		V <sub>CC</sub> = 3.3 V ±0.3 V	0	10	
	$V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$		0	5	
$\theta_{\sf JA}$	Thermal Resistance US8		-	250	°C/W
		MicroPak-8	-	232	1

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. Unused inputs must be held HIGH or LOW. They may not float.

# NC7WZ32

# DC ELECTICAL CHARACTERISTICS

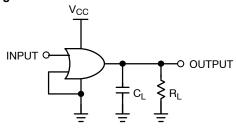
					T <sub>A</sub> = +25°C			T <sub>A</sub> = -40	to +85°C	
Symbol	Parameter	Co	nditions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	H HIGH Level Input Voltage			1.65 to 1.95	0.65 V <sub>CC</sub>	-	-	0.65 V <sub>CC</sub>	_	V
				2.3 to 5.5	0.7 V <sub>CC</sub>	-	-	0.7 V <sub>CC</sub>	_	
V <sub>IL</sub>	LOW Level Input			1.65 to 1.95	-	-	0.35 V <sub>CC</sub>	_	0.35 V <sub>CC</sub>	V
	Voltage			2.3 to 5.5	-	-	0.3 V <sub>CC</sub>	_	0.3 V <sub>CC</sub>	
V <sub>OH</sub>	HIGH Level Output	$V_{IN} = V_{IH}$	I <sub>OH</sub> = -100 μA	1.65	1.55	1.65	-	1.55	_	V
	Voltage	or V <sub>IL</sub> ,		2.3	2.2	2.3	-	2.2	_	1
				3.0	2.9	3.0	-	2.9	_	1
				4.5	4.4	4.5	-	4.4	_	1
			I <sub>OH</sub> = -4 mA	1.65	1.29	1.52	-	1.29	_	1
			I <sub>OH</sub> = -8 mA	2.3	1.9	2.15	-	1.9	_	1
			I <sub>OH</sub> = -16 mA	3.0	2.4	2.80	-	2.4	_	1
			I <sub>OH</sub> = -24 mA	3.0	2.3	2.68	-	2.3	_	
			$I_{OH} = -32 \text{ mA}$	4.5	3.8	4.20	-	3.8	_	
V <sub>OL</sub>	L LOW Level Output $V_{IN} = V_{IH}$ or $V_{IL}$ ,	$V_{IN} = V_{IH}$	I <sub>OL</sub> = 100 μA	1.65	-	0.0	0.1	_	0.1	V
		or v <sub>IL</sub> ,		2.3	-	0.0	0.1	-	0.1	
				3.0	-	0.0	0.1	-	0.1	
				4.5	-	0.0	0.1	-	0.1	
			I <sub>OL</sub> = 4 mA	1.65	-	0.08	0.24	_	0.24	
			I <sub>OL</sub> = 8 mA	2.3	_	0.10	0.3	_	0.3	1
			I <sub>OL</sub> = 16 mA	3.0	_	0.15	0.4	_	0.4	1
			I <sub>OL</sub> = 24 mA	3.0	_	0.22	0.55	_	0.55	1
			I <sub>OL</sub> = 32 mA	4.5	-	0.22	0.55	_	0.55	
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5	V <sub>IN</sub> = 5.5 V, GND		-	_	±0.1	-	±1	μΑ
l <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> or V <sub>OUT</sub> = 5.5 V		0.0	-	_	1	-	10	μΑ
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = 5.5 \	/, GND	1.65 to 5.5	-	_	1	-	10	μΑ

#### **AC ELECTRICAL CHARACTERISTICS**

				T <sub>A</sub> = +25°C			T <sub>A</sub> = -40 to +85°C		
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay	C <sub>L</sub> = 15 pF,	1.8 ±0.15	-	5.8	10.5	-	11	ns
	(Figure 5, 7)	$R_L = 1 M\Omega$	2.5 ±0.2	-	3.5	5.8	-	6.2	
			3.3 ±0.3	-	2.6	3.9	-	4.3	
			5.0 ±0.5	-	1.8	3.1	-	3.3	
		C <sub>L</sub> = 50 pF,	3.3 ±0.3	-	3.2	4.8	-	5.2	
		$R_L = 500 \Omega$	5.0 ±0.5	-	2.4	3.7	-	4.0	
C <sub>IN</sub>	Input Capacitance		0	-	2.5	-	-	-	pF
	Power Dissipation Capacitance	(Note 2)	3.3	-	14	-	-	-	pF
	(Figure 6)		5.0	-	18	-	-	-	

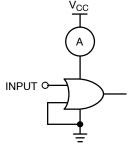
C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. (see Figure 6) C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = (C<sub>PD</sub>) (V<sub>CC</sub>) (f<sub>IN</sub>) + (I<sub>CC</sub>static).

## **AC Loading and Waveforms**



 $C_L$  includes load and stray capacitance Input PRR = 1.0 MHz,  $t_W = 500 \ \text{ns}$ 

Figure 5. AC Test Circuit



 $\begin{aligned} & \text{Input} = \text{AC Waveforms; } t_r = t_f = 1.8 \text{ ns;} \\ & \text{PRR} = 10 \text{ MHz; } \text{Duty Cycle} = 50\%. \end{aligned}$ 

Figure 6.  $I_{CCD}$  Test Circuit

# $t_{r} = 3 \text{ ns} \qquad t_{f} = 3 \text{ ns} \qquad V_{CC}$ $10\% \qquad 50\% \qquad 50\% \qquad 10\% \qquad GND$ $0UTPUT \qquad 50\% \qquad 50\% \qquad V_{OH}$

Figure 7. AC Waveforms

#### **ORDERING INFORMATION**

Order Number	Top Mark	Package	Shipping <sup>†</sup>
NC7WZ32K8X	WZ32	8-Lead US8, JEDEC MO-187, Variation CA	3000 / Tape & Reel
NC7WZ32K8X-L22236	WZ32	3.1 mm Wide	3000 / Tape & Reel
NC7WZ32L8X	N5	8-Lead MicroPak, 1.6 mm Wide	5000 / Tape & Reel
NC7WZ32L8X-L22185	N5	(Pb-Free)	5000 / Tape & Reel

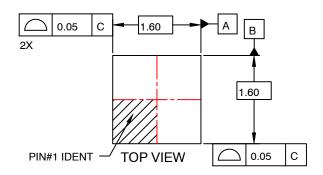
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

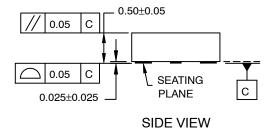
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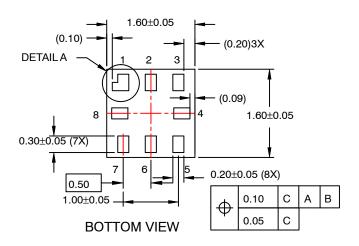
<sup>3.</sup> Pb-Free package per JEDEC J-STD-020B.

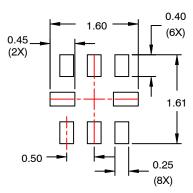
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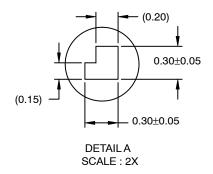




RECOMMENDED LAND PATTERN

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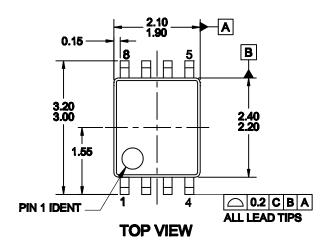


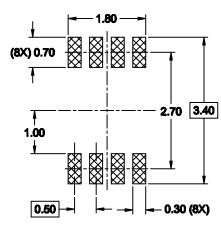
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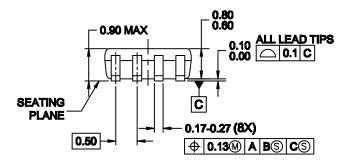
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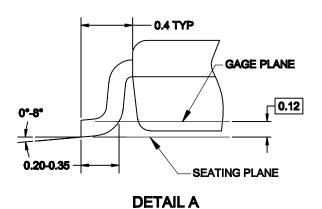
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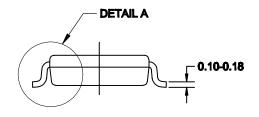


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# **SIDE VIEW**





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